Reportable Substances in Components

Package Type :		Component Weight :		0.081257 grams
	TSSOP	Document No :	TSSOP-24LD-PBY-RS-3	
Lead #:	**24**	Process Type :	Standard D/A & Pb-Free Lead Finish	

No	Material	Content in %	Content in gram	Substance Name	CAS No	Content in gram	% to Content	% to Unit	PPM
1	Molding Compound	57.294%	0.046555						
				Silica Fused	60676-86-0	0.040038	86.000%	49.272%	
				Epoxy Resin	Trade secret	0.003724	8.000%	4.584%	
				Phenol Resin	Trade secret	0.002654	5.700%	3.266%	
				Carbon Black	1333-86-4	0.000140	0.300%	0.172%	
2	Copper Alloy Frame	37.318%	0.030324						
				Cu	7440-50-8	0.029171	96.200%	35.900%	
				Ni	7440-02-0	0.000910	3.000%	1.120%	
				Si	7440-21-3	0.000197	0.650%	0.243%	
				Mg	7439-95-4	0.000045	0.150%	0.056%	560
3	Spot Silver Plating	1.033%	0.000839						
				Ag	7440-22-4	0.000839	100.000%	1.033%	
4	Silver Die Attach Epoxy	0.295%	0.000239						
				Silver	7440-22-4	0.000180	75.000%	0.221%	
				Epoxy Resin	9003-36-5	0.000036	15.000%	0.044%	442
				1,4-Bis (2,3-epoxypropoxy)butane	2425-79-8	0.000012	5.000%	0.015%	148
				Aromatic Amine	Trade secret	0.000012	5.000%	0.015%	148
5	Gold Wire	1.319%	0.001071						
				Au	7440-57-5	0.001071	100.000%	1.319%	
6	External Lead Plating	1.320%	0.001072						
				Sn	7440-31-5	0.001072	100.000%	1.320%	
7	Silicon Die	1.423%	0.001156						
				Si	7440-21-3	0.001156	100.000%	1.423%	

Rev	ECN	Originator	Change	Reason
A	083011HC05	S. YEH	New Release	New